CELADON™

A Wholly Owned Subsidiary of MPI CORPORATION

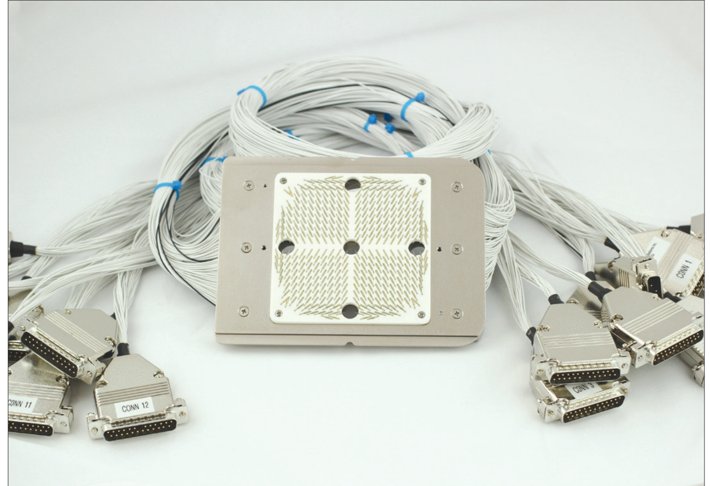
HIGH-DENSITY MULTI-SITE TESTING

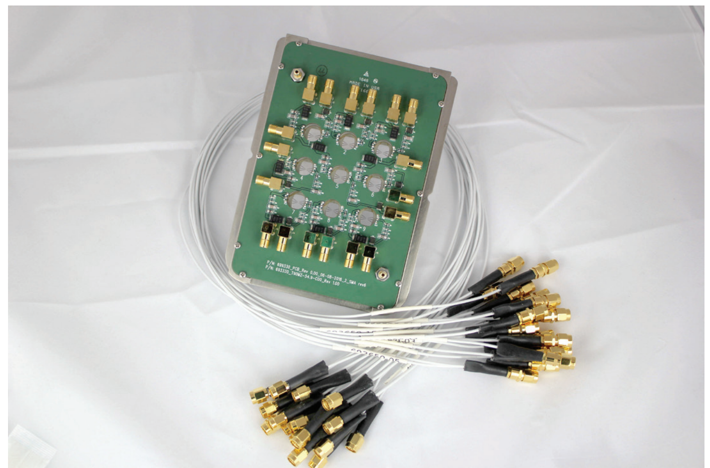
T90 SERIES

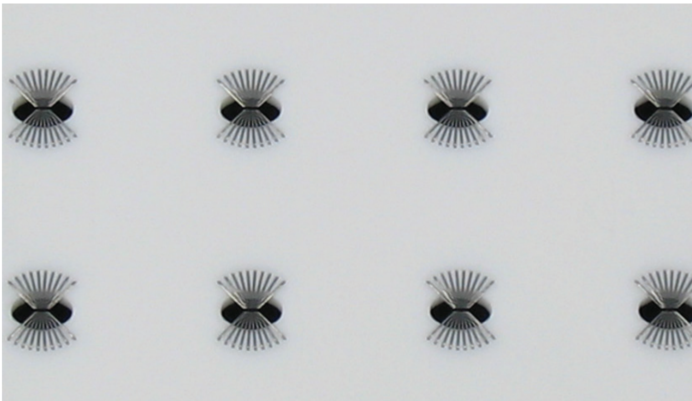
Multi-site modeling and Characterization, Wafer Level Reliability, and Burn-in

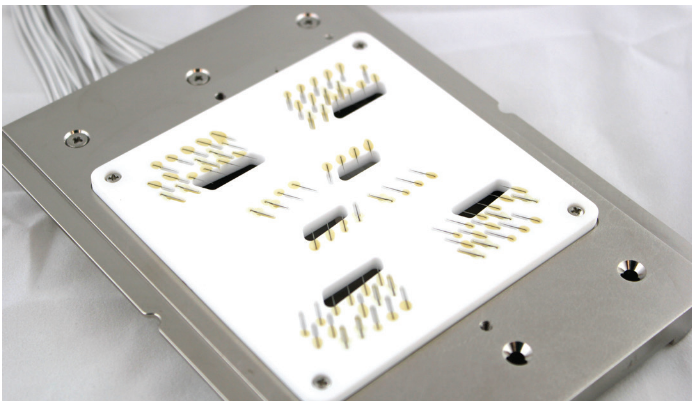
T90 Series probe cards are compatible with industry-standard 4.5" rails, but can be configured with up to 500 probes for dense multi-site wafer level reliability testing. With an effective operating temperature range from -65° to 300° [optional 400°C], T90 probe cards can deliver dependable and accurate low leakage test data.

The T90 probe card is a durable, reliable, and rugged solution for high density wafer level reliability testing, and at the same time are compact and easy to use with a variety of testing platforms.









HIGH-DENSITY MULTI-SITE TESTING IN A CONVENIENT 4.5" FORMAT

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